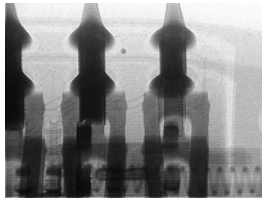
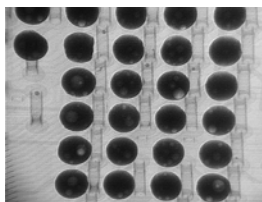


RTX-113HV MicroTech

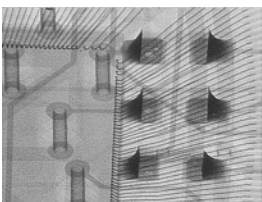
A High Magnification X-ray Inspection System



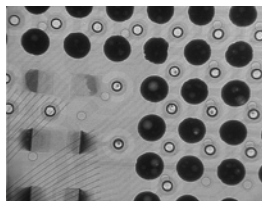
Inspect Solder in Connector



Angle viewing of voids in BGA



Wire bonds at angle



Cold solder joint on BGA

The RTX-113HV MicroTech X-ray System is engineered for high-resolution inspection of PC boards and other packaged devices in a production environment. This machine features a compact footprint and an exceptionally user-friendly interface, making it an ideal solution for efficient and precise quality control.

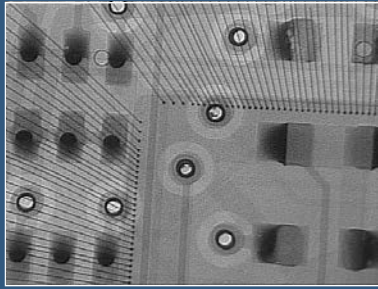
It utilizes an 80 kV, 5-micron focal spot X-ray tube, providing the resolution necessary to clearly see wire bonds. The system's cabinet can accommodate PC boards up to 18" x 24" in size. Additionally, the motorized tray offers a versatile scan area of 15" x 15" in the x-y axis, ensuring a thorough X-ray inspection.

An adjustable wedge is included, allowing you to position the object at your preferred angle for optimal inspection. The system offers up to 100x geometric magnification and 225x optical magnification, making it ideal for inspecting BGAs, QFNs, LEDs, sensors, medical devices, and other packaged devices.

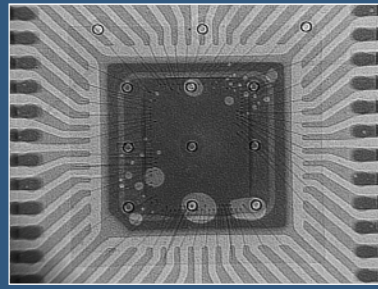
It features Glenbrook's patented XRTV X-ray camera, enhanced with Crystal X technology for superior brightness and contrast.



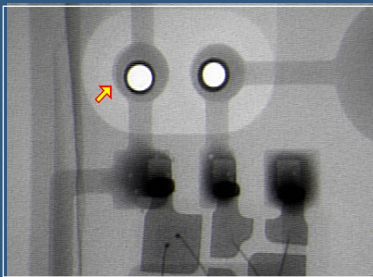
Precision X-ray Inspection with High Magnification



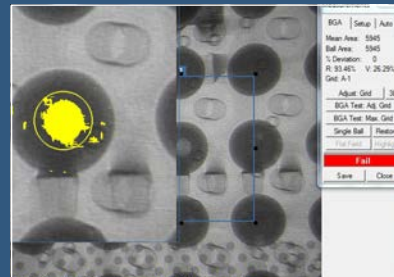
Wire bonds



QFN Inspection



*Inner layer shift on 6 mil.
drilled hole*



Void Analysis on BGA

Specifications

- Magnification up to 100x geometric + 225x optical
- Motorized X-Y Positioner Travel: 19" x 15"
- Voltage: 120v or 220v
- Contrast Resolution: Can resolve .001 gold wire
- Spatial Resolution: 20lp/mm up to 100lp/mm
- Anode Voltage: 40Kv-80Kv (PC Controlled)
- Anode Current: 20-150 microamps
- X-ray Tube Focal Spot: 5 microns
- Machine Dimensions: 60" x 33" x 51"
- Cabinet Interior Dimensions: 39" x 29" x 14"

